

REMARKS

Claims 1, 2 and 4 through 7 are now pending in this application. In response to the non-final Office Action dated April 5, 2005, claim 1 has been amended and claim 3 has been cancelled. Care has been taken to avoid the addition of new matter. A petition for two month extension of the period for response to the Office Action, and appropriate fee charge authorization, are filed herewith. Allowance of the application is respectfully solicited.

Claim 1 has been rejected under 35 U. S. C. § 102(e) as being anticipated by the published patent application U.S. 2003/0032263 A1 (Nagao). In response, claim 1 has been amended to recite, *inter alia*, the following:

wherein the monitoring pad includes two or more exposed surfaces divided via a space that is approximately parallel to the longitudinal direction of the dicing area, and

the two or more exposed surfaces are electrically connected with each other via a metal wiring of an inner layer.

The invention, as recited above, requires that the two or more exposed surfaces are electrically connected with each other so that they act as one unitized probing pad. The unitized probing pad has an enlarged area to connect with a test probe. Unitization of the probing pad is effective to enhance reliability of electrical connection with the test probe.

In contrast, Nagao et al. discloses a semiconductor wafer which has some independent probing pads 19. Neither Nagao nor any of the cited prior art discloses or teaches such a unitized probing pad as recited in claim 1.

Claim 2 has been indicated to be drawn to allowable subject matter. As claim 3 has been cancelled, it is submitted that all rejections of record have been overcome. To the extent necessary, a petition for an extension of time under 37 C.F.R. 1.136 is hereby made. Please

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charge any shortage in fees due in connection with the filing of this paper, including extension of time fees, to Deposit Account 500417 and please credit any excess fees to such deposit account.

Respectfully submitted,

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